



## **General Description**

The MAX5984 is a single-port, power-sourcing equipment (PSE) power controller designed for use in IEEE® 802.3af/at-compliant PSE. This device provides powered device (PD) discovery, classification, current limit, and DC and AC load-disconnect detections. The MAX5984 operates automatically without the need for any software programming and features an integrated power MOSFET and sense resistor. The device also supports new Class 5 and 2-Event classification for detection and classification of high-power PDs. The MAX5984 provides up to 40W to a single port (Class 5 enabled) and still provides highcapacitance detection for legacy PDs.

The MAX5984 provides input undervoltage lockout (UVLO), input overvoltage lockout, overtemperature detection, output voltage slew-rate limit during startup, and LED status indication.

The MAX5984 is available in a space-saving, 28-pin TQFN (5mm x 5mm) power package, and is rated for the extended (-40°C to +85°C) temperature range.

### **Features**

- ♦ IEEE 802.3af/at Compliant
- ♦ Up to 40W for Single-Port PSE Applications
- ♦ Integrated 0.5Ω Power MOSFET and Sense Resistor
- ◆ 2-Event Pin-Select (MAX5984A/MAX5984B)
- **♦ PD Detection and Classification**
- ♦ Programmable Current Limit for Class 5 PDs
- ♦ High-Capacitance Detection for Legacy Devices
- ♦ Supports Both DC and AC Load Removal **Detections**
- ♦ Current Foldback and Duty Cycle-Controlled **Current Limit**
- **♦ LED Indicator for Port Status**
- **♦ Direct Fast-Shutdown Control Capability**
- ♦ Space-Saving, 28-Pin TQFN (5mm x 5mm) **Package**

## **Applications**

Single-Port PSE End-Point Applications

Single-Port PSE Power Injectors (Midspan Applications)

PoE Repeaters

Switches/Routers

Industrial Automation Equipment

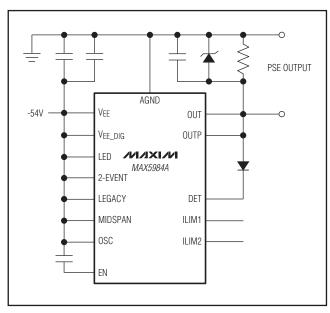
Wireless LAN Access Point/WiMAX® Base Stations

## **Ordering Information**

PART	PIN- SELECT	TEMP RANGE	PIN- PACKAGE
MAX5984AETI+	2-EVENT	-40°C to +85°C	28 TQFN-EP*
MAX5984BETI+**	2-EVENT	-40°C to +85°C	28 TQFN-EP*
MAX5984CETI+**	PWMEN	-40°C to +85°C	28 TQFN-EP*
MAX5984DETI+	LSCEN	-40°C to +85°C	28 TQFN-EP*

<sup>+</sup>Denotes a lead(Pb)-free/RoHS-compliant package.

## **Typical Operating Circuit**



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/U/IXI/U

Maxim Integrated Products 1

<sup>\*</sup>EP = Exposed pad.

<sup>\*\*</sup>Future product—Contact factory for availability.

### **ABSOLUTE MAXIMUM RATINGS**

(Voltages referenced to VEE, unle	as otherwise noted )
. 5	,
AGND, DET, LED	0.3V to +80V
OUT	0.3V to (V <sub>AGND</sub> + 0.3V)
OUTP	6V to (V <sub>AGND</sub> + 0.3V)
VEE_DIG	
OSC	0.3V to +6V
EN, 2-EVENT/PWMEN/LSCEN, MI	DSPAN,
LEGACY, ILIM1, ILIM2	0.3V to +4V
Maximum Current Into LED	40mA

Maximum Current Into OUT	Internally regulated
Continuous Power Dissipation (T <sub>A</sub> = +70°C	)
TQFN (derate 34.5mW/°C above +70°C).	2758.6mW
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
Soldering Temperature (reflow)	+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### PACKAGE THERMAL CHARACTERISTICS (Note 1)

**TQFN** 

Junction-to-Ambient Thermal Resistance	29°C
Junction-to-Case Thermal Resistance	2°C

**Note 1:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to <a href="https://www.maxim-ic.com/thermal-tutorial">www.maxim-ic.com/thermal-tutorial</a>.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{AGND} - V_{EE} = 32V \text{ to } 60V, T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ all voltages are referenced to } V_{EE}, \text{ unless otherwise noted.}$  Typical values are at VAGND - VEE = 54V, T<sub>A</sub> = +25°C. Currents are positive when entering the pin and negative otherwise.) (Note 2)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
POWER SUPPLIES	•						
Operating Voltage Range	Vagnd	VAGND - VEE		32		60	V
Supply Current	IEE		all logic inputs unconnected, AGND in power mode		2.5	4	mA
CURRENT LIMIT							
		Maximum	Class 0, 1, 2, 3	400	420	441	
		ILOAD	Class 4	684	720	756	
O manak Limit	a	allowed during current-limit conditions, VOUT = 0V (Note 3)	Class 5 if ILIM1 = V <sub>EE</sub> , ILIM2 = unconnected	807	850	893	Λ
Current Limit	ILIM		Class 5 if ILIM1 = unconnected, ILIM2 = VEE	855	900	945	mA mA
			Class 5 if ILIM1 = VEE, ILIM2 = VEE	902	950	998	
Foldback Initial OUT Voltage	VFLBK_ST	VAGND - VOL limit starts fo		27		V	
Foldback Final OUT Voltage	VFLBK_END	VAGND - VOL limit reaches		10		V	
Minimum Foldback Current Limit Threshold	lTH_FB	V <sub>OUT</sub> = V <sub>AG</sub>	ND		166		mA

## **ELECTRICAL CHARACTERISTICS (continued)**

(VAGND - VEE = 32V to 60V, TA = -40°C to +85°C, all voltages are referenced to VEE, unless otherwise noted. Typical values are at VAGND - VEE = 54V, TA = +25°C. Currents are positive when entering the pin and negative otherwise.) (Note 2)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
OVERCURRENT							
			Class 0, 1, 2, 3	351	370	389	
		Overcurrent	Class 4	602	634	666	]
Overeument Threshold	lo: =	threshold allowed for	Class 5 if ILIM1 = VEE, ILIM2 = unconnected	710	748	785	mA
Overcurrent Threshold	ICUT	$t \le t_{FAULT}$ , $V_{OUT} = 0V$	Class 5 if ILIM1 = unconnected, ILIM2 = VEE	752	792	832	
		(Note 3)	Class 5 if ILIM1 = V <sub>EE</sub> , ILIM2 = V <sub>EE</sub>	794	836	878	
INTERNAL POWER							
DMOS On-Resistance	Proyoni	Measured from OUT to	TA = +25°C		0.5	0.9	
DINOS OII-nesistance	RDS(ON)	VEE, IOUT = 100mA	TA = +85°C		0.6	1.3	Ω
Power-Off OUT Leakage Current	IOUT_LEAK	V <sub>EN</sub> = V <sub>EE</sub> , \	OUT = VAGND			10	μΑ
SUPPLY MONITORS							
VEE Undervoltage Lockout	VEE_UVLO	VAGND - VEE	, V <sub>AGND</sub> increasing		28.5		V
VEE Undervoltage Lockout Hysteresis	VEE_UVLOH		Port is shutdown if: VAGND - VEE < VEE_ UVLO - VEE_UVLOH		3		V
VEE Overvoltage Lockout	VEE_OV	VAGND - VEE	Vagnd - Vee > Vee_ov, Vagnd increasing		62.5		V
VEE Overvoltage Lockout Hysteresis	VEE_OVH				1		V
Thermal Shutdown Threshold	T <sub>SHD</sub>	Port is shutdown and device resets if the junction temperature exceeds this limit, temperature increasing			+150		°C
Thermal Shutdown Hysteresis	TSHDH	Temperature	decreasing		20		°C
OUTPUT MONITOR		· · · · ·					
OUT Input Current	IBOUT	Vout = Vag	ND, probing phases			6	μΑ
Idle Pullup Current at OUT	IDIS	OUTP discharge current, detection and classification off, port shutdown,  VOUTP = VAGND - 2.8V		200		265	μА
Short to VEE Detection Threshold	DCNTH	VOUT - VEE, during detec	V <sub>OUT</sub> decreasing, enabled stion	1.5	2.0	2.5	V
Short to VEE Detection Threshold Hysteresis	DCN <sub>H</sub> Y				220		mV
LOAD DISCONNECT							
DC Load-Disconnect Threshold	Ірстн	Minimum load current allowed before disconnect (DC disconnect active), VOUT = 0V		5	7.5	10	mA
AC Load-Disconnect Threshold	ГАСТН		DET, for IDET < IACTH the off (AC disconnect active)	115	130	145	μΑ

## **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{AGND} - V_{EE} = 32V \text{ to } 60V, T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ all voltages are referenced to } V_{EE}, \text{ unless otherwise noted.}$  Typical values are at VAGND - VEE = 54V, T<sub>A</sub> = +25^{\circ}\text{C}. Currents are positive when entering the pin and negative otherwise.) (Note 2)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
Triangular Wave Peak-to-Peak Voltage Amplitude	AMPTRW	Measured at DET, referred to AGND		3.85	4	4.2	V
OSC Pullup/Pulldown Currents	losc	Measured at	OSC	26	32	39	μΑ
ACD_EN Threshold	VACD_EN	Vosc - Vee > disconnect	V <sub>ACD_EN</sub> to activate AC	270	330	380	mV
Load Disconnect Timer	tDISC	disconnect ad	SENSE < IDCTH (DC ctive) or IDET < IACTH (AC ctive) to gate shutdown	300		400	ms
DETECTION	•						
Detection Probe Voltage (First Phase)	VDPH1	VAGND - VDE	T during the first detection	3.8	4	4.2	V
Detection Probe Voltage (Second Phase)	VDPH2	VAGND - VDE detection pha	T during the second ase	9	9.3	9.6	V
Current-Limit Protection	I <sub>DLIM</sub>	VDET = VAGN current throug	D during detection, measure gh DET	1.50	1.75	2.00	mA
Short-Circuit Threshold	VDCP	If VAGND - VC detection pha is detected		1		V	
Open-Circuit Threshold	ID_OPEN	First point measurement current threshold for open condition			8		μΑ
Resistor Detection Window	RDOK	(Note 4)		19		26.5	kΩ
Resistor Rejection Window	RDBAD		ects lower values ects higher values	32		15.5	kΩ
CLASSIFICATION							
Classification Probe Voltage	VCL	VAGND - VDE	T during classification	16		20	V
Current-Limit Protection	ICILIM	VDET = VAGND, during classification measure current through DET		65		80	mA
		Classification	Class 0, Class 1	5.5	6.5	7.5	
Classification Current		current	Class 1, Class 2	13.0	14.5	16.0	mA
Classification Current Thresholds	ICL	thresholds between	Class 2, Class 3	21	23	25	
			Class 3, Class 4	31	33	35	
		classes Class 4 upper limit (Note 5)		45	48	51	
Mark Event Voltage	VMARK	VAGND - VDET during mark event		8		10	V
Mark Event Current Limit	IMARK_LIM	V <sub>DET</sub> = V <sub>AGND</sub> , during mark event measure current through DET		55		80	mA

## **ELECTRICAL CHARACTERISTICS (continued)**

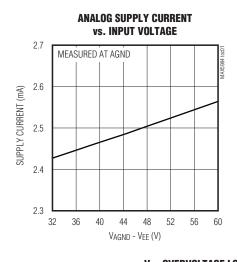
 $(V_{AGND} - V_{EE} = 32V \text{ to } 60V, T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ all voltages are referenced to } V_{EE}, \text{ unless otherwise noted.}$  Typical values are at VAGND - VEE = 54V, T<sub>A</sub> = +25^{\circ}\text{C}. Currents are positive when entering the pin and negative otherwise.) (Note 2)

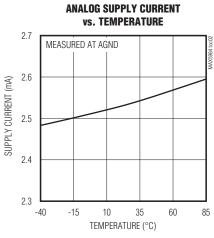
PARAMETER	SYMBOL	CONDITIONS		TYP	MAX	UNITS
DIGITAL INPUTS/OUTPUTS (Vo	Itages refere	nced to VEE)				
Digital Input Low	VIL				0.8	V
Digital Input High	VIH		2.4			V
Internal Input Pullup Current	IPU	Pullup current to internal digital supply to set default values	3	5	7	μA
LED Output Low Voltage	VLED_LOW	ILED = 10mA, PWM disabled, port power-on			0.8	V
LED Output Leakage	ILED_LEAK	PWM disabled, shutdown mode, V <sub>LED</sub> = 60V			10	μΑ
PWM Frequency				25		kHz
PWM Duty Cycle				6.25		%
TIMING						
Startup Time	tstart	Time during which a current limit set to 420mA is allowed, starts when power is turned on	50	60	70	ms
Fault Time	tFAULT	Maximum allowed time for an overcurrent condition set by ICUT after startup	50	60	70	ms
Detection Reset Time	tME	Time allowed for the port voltage to reset before detection starts		80	90	ms
Detection Time	tDET	Maximum time allowed before detection is completed			330	ms
Midspan Mode Detection Delay	tDMID		2	2.2	2.4	S
Classification Time	tCLASS	Time allowed for classification		19	23	ms
Mark Event Time		Time allowed for mark event	7	9	11	ms
VEEUVLO Turn-On Delay	tDLY	Time VAGND must be above the VEEUVLO thresholds before the device operates		5.2		ms
Restart Timer	trestart	Time the device waits before turning on after an overcurrent fault		16 x tfault		ms

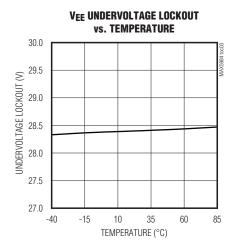
- Note 2: This device is production tested at TA = +25°C. Limits at TA = -40°C and TA = +85°C are guaranteed by design.
- Note 3: If ILIM1 and ILIM2 are both unconnected, Class 5 detection is disabled. See the Class 5 PD Classification section and Table 3 for details and settings.
- Note 4: RDOK = (VOUT2 VOUT1)/(IDET2 IDET1). VOUT1, VOUT2, IDET2, and IDET1 represent the voltage at OUT and the current at DET during phase 1 and 2 of the detection, respectively.
- Note 5: If Class 5 is enabled, this is the classification current thresholds from Class 4 to Class 5.

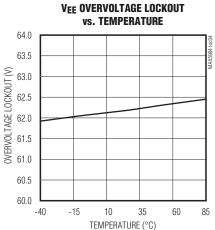
## **Typical Operating Characteristics**

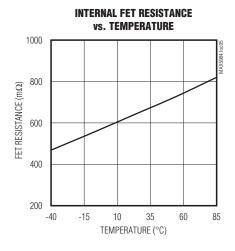
 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

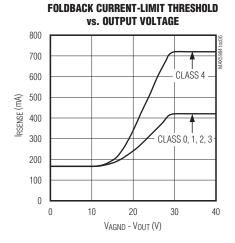


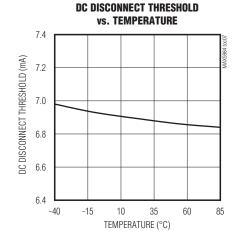








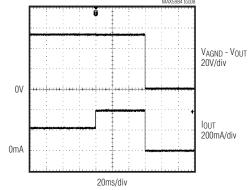




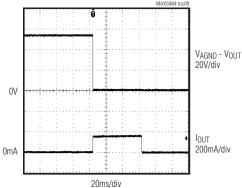
**Typical Operating Characteristics (continued)** 

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

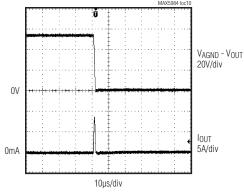
### OVERCURRENT TIMEOUT (240 $\Omega$ TO 138 $\Omega$ )



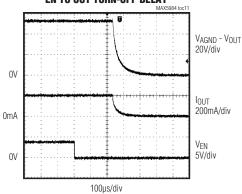
## SHORT-CIRCUIT RESPONSE TIME



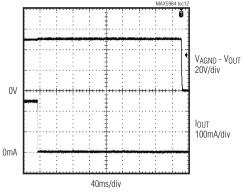
#### **SHORT-CIRCUIT TRANSIENT RESPONSE**



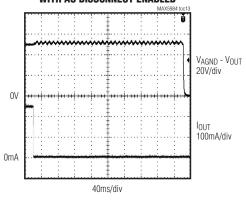
#### **EN TO OUT TURN-OFF DELAY**



## ZERO-CURRENT DETECTION WAVEFORM WITH DC DISCONNECT ENABLED

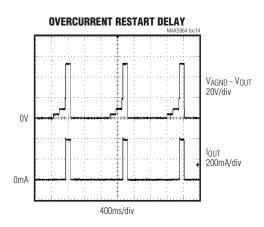


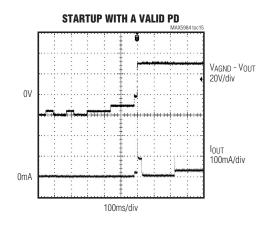
## ZERO-CURRENT DETECTION WAVEFORM WITH AC DISCONNECT ENABLED



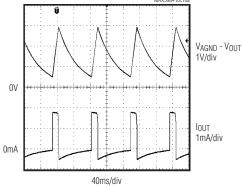
**Typical Operating Characteristics (continued)** 

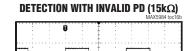
 $(T_A = +25$ °C, unless otherwise noted.)

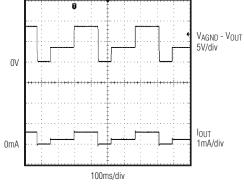




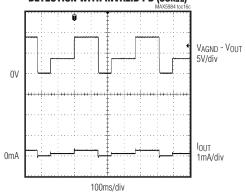




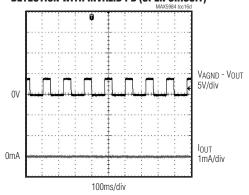




### DETECTION WITH INVALID PD (33 $k\Omega$ )



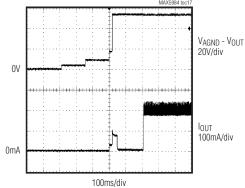
### **DETECTION WITH INVALID PD (OPEN CIRCUIT)**



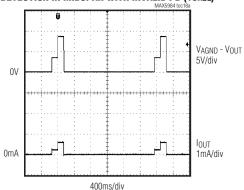
\_Typical Operating Characteristics (continued)

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

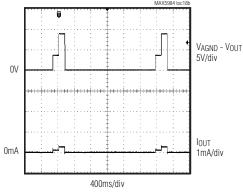
### STARTUP IN MIDSPAN WITH A VALID PD



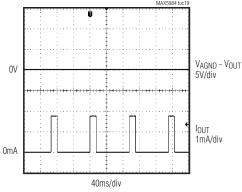
### DETECTION IN MIDSPAN WITH INVALID PD (15 $k\Omega$ )



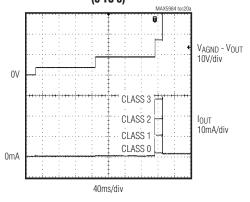
### DETECTION IN MIDSPAN WITH INVALID PD (33 $k\Omega$ )



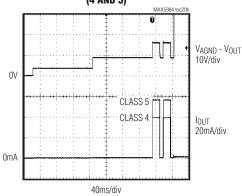
**DETECTION IN OUTPUT SHORTED TO AGND** 



## CLASSIFICATION WITH DIFFERENT PD CLASSES (0 TO 3)



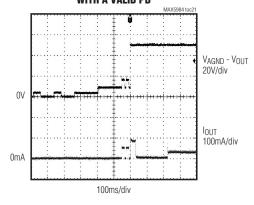
## CLASSIFICATION WITH DIFFERENT PD CLASSES (4 AND 5)



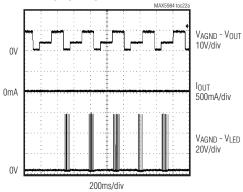
Typical Operating Characteristics (continued)

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

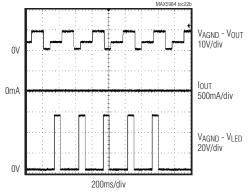
## STARTUP USING 2-EVENT CLASSIFICATION WITH A VALID PD



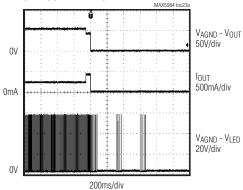
#### **LED DETECTION FAULT WITH PWM ENABLED**



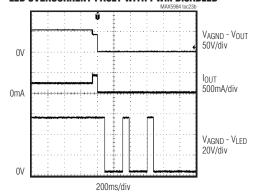
#### **LED DETECTION FAULT WITH PWM DISABLED**



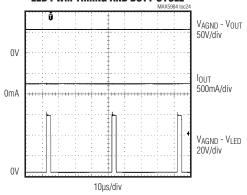
#### LED OVERCURRENT FAULT WITH PWM ENABLED



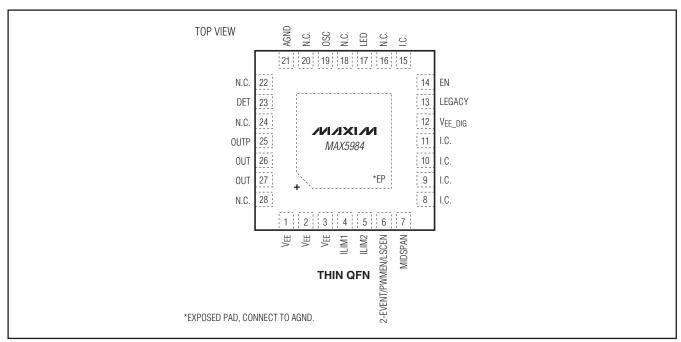
### LED OVERCURRENT FAULT WITH PWM DISABLED



### LED PWM TIMING AND DUTY CYCLE



## **Pin Configuration**



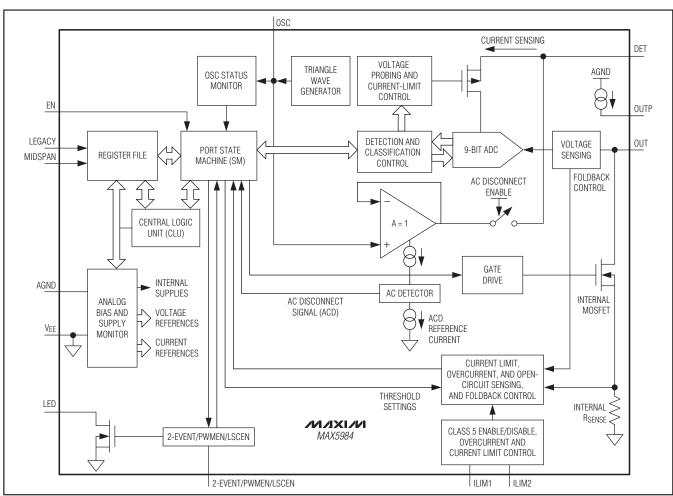
## Pin Description

PIN	NAME	FUNCTION
1, 2, 3	VEE	Analog Low-Side Supply Input. Bypass with an external 100V, 47µF capacitor in parallel with a 100V, 0.1µF ceramic capacitance between AGND and VEE.
4	ILIM1	Class 5 Current-Limit Digital Adjust 1. Referenced to VEE. ILIM1 is internally pulled up to the digital supply. Use ILIM1 with ILIM2 to enable Class 5 operation and to adjust the Class 5 current-limit value. See the <i>Electrical Characteristics</i> table and Table 3 for details.
5	ILIM2	Class 5 Current-Limit Digital Adjust 2. Referenced to V <sub>EE</sub> . ILIM2 is internally pulled up to the digital supply. Use ILIM2 with ILIM1 to enable Class 5 operation and to adjust the Class 5 current-limit value. See the <i>Electrical Characteristics</i> table and Table 3 for details.
	2-EVENT (MAX5984A/ MAX5984B)	2-Event Classification Select. Referenced to VEE. 2-EVENT is internally pulled up to the digital supply. Leave unconnected to disable 2-Event classification. Force low to enable the 2-Event classification. See the <i>2-Event PD Classification</i> section for more details. <b>Change status of this bit only when the part is in reset state.</b> The MAX5984C/MAX5984D are enabled.
6	PWMEN (MAX5984C)	PWM Control Logic Input. Referenced to V <sub>EE</sub> . PWMEN is internally pulled up to the digital supply. Leave unconnected to enable the internal PWM to drive the LED pin. Force low to disable the internal PWM. The MAX5984A/MAC5984B/MAX5984D are enabled.
	LSCEN (MAX5984D)	Load Stability Check Function Select. Referenced to VEE. LSCEN is internally pulled up to the digital supply. Leave unconnected to enable the load stability check function. Force low to disable the load stability check function. <b>Change status of this bit only when the part is in reset state.</b> The MAX5984A is disabled but the MAX5984B/MAX5984C are enabled.

## Pin Description (continued)

PIN	NAME	FUNCTION
7	MIDSPAN	Detection Collision Avoidance Logic Input. Referenced to VEE. MIDSPAN is internally pulled up to the digital supply. Leave unconnected to activate the detection collision avoidance circuitry for midspan PSE systems. Force low to disable this function for an end-point PSE system. The MIDSPAN logic level latches after the device is powered up or after a reset condition.
8–11, 15	I.C.	Internally Connected. Connect I.C. to VEE.
12	VEE_DIG	Digital Low-Side Supply Input. Connect to VEE externally.
13	LEGACY	Legacy Detection Logic Input. Referenced to V <sub>EE</sub> . LEGACY is internally pulled up to the digital supply. Leave unconnected to activate the legacy PD detection. Force low to disable this function. The LEGACY logic level latches after the device is powered up or after a reset condition.
14	EN	Enable Input. Referenced to V <sub>EE</sub> . EN is internally pulled up to the digital supply. Leave unconnected to enable the device. Force low for at least 40µs to reset the device. The MIDSPAN, OSC, and LEGACY states latch-in when the reset condition is removed (low-to-high transition).
16, 18, 20, 22, 24, 28	N.C.	No Connection. Not internally connected. Leave N.C. unconnected.
17	LED	LED Indicator Open-Drain Output. Referenced to VEE. LED can sink 10mA and can drive an external LED directly. Blinking functionality is provided to signal different conditions (see the <i>PWM and LED Signals</i> section). Connect LED to AGND externally or to an external supply (if available) through a series resistance (Figures 6 and 7).
19	OSC	AC Disconnect Triangular Wave Output. Bypass with a 100nF (±10% tolerance) external capacitor to VEE to enable the AC disconnect function. Connect OSC to VEE to disable the AC disconnect function and to activate the DC disconnect function. The OSC state latches after the device is powered up or after a reset condition.
21	AGND	High-Side Supply Input
23	DET	Detection/Classification Voltage Output. DET is used to set the detection mark event and classification probe voltages and for the AC current sensing when using the AC disconnect function. To use the AC disconnect function, place a $1k\Omega$ and $0.47\mu F$ RC series in parallel with the external protection diode to OUTP (Figure 7).
25	OUTP	Port Pullup Output. OUTP is used to pull up the port voltage to AGND when needed. If AC disconnect is used, connect OUTP to the anode of the AC-blocking diode. If AC disconnect is not used, connect OUTP to OUT (Figures 6 and 8). Bypass OUTP to AGND with a 100V, 0.1µF ceramic capacitor.
26, 27	OUT	Integrated MOSFET Output. If DC disconnect is used, connect the port output to OUTP (Figures 6 and 8). If the AC disconnect function is used, connect OUT to the cathode of the AC-blocking diode (Figure 7).
_	EP	Exposed Pad. Connect EP to VEE externally. See the Layout Procedure section for details.

## Simplified Diagram



## **Detailed Description**

The MAX5984 is a single-port, PSE power controller designed for use in IEEE 802.3af/IEEE 802.3at-compliant PSE. This device provides PD discovery, classification, current limit, and DC and AC load-disconnect detections. The MAX5984 operates automatically without the need for any software programming and features an integrated power MOSFET and sense resistor. The device also supports new Class 5 and 2-event classification for detection and classification of high-power PDs. The MAX5984 provides up to 40W to a single port (Class 5 enabled) and still provides high-capacitance detection for legacy PDs.

The MAX5984 provides input UVLO, input overvoltage lockout, overtemperature detection, output voltage slew-rate limit during startup, and LED status indication.

#### Reset

The MAX5984 is reset by any of the following conditions:

- Power-up. Reset condition is cleared once VEE rises above the UVLO threshold.
- 2) Hardware reset. Reset occurs once the EN input is driven low (> 40µs typ) any time after power-up. The device exits the reset condition once the EN input is driven high again.
- 3) Thermal shutdown. The device enters thermal shutdown at +150°C. The device exits thermal shutdown and is reset once the temperature drops below 130°C.

During a reset, the MAX5984 latches in the state of MIDSPAN, LEGACY, and OSC. During normal operation, changes to these inputs are ignored.

#### Midspan Mode

In midspan mode, the device adopts cadence timing during the detection phase. When cadence timing is enabled and a failed detection occurs, the port waits between 2s and 2.4s before attempting to detect again. Midspan mode is activated by setting MIDSPAN high and then powering or resetting the device. By default, the MIDSPAN input is internally pulled high. Force MIDSPAN low to disable this function.

#### **Automatic Operation**

The MAX5984 operates automatically after the reset condition is cleared. The device performs detection and classification, and powers up the port automatically once a valid PD is detected at the port. If a valid PD is not connected at the port, the MAX5984 repeats the detection routine continuously until a valid PD is connected.

#### **PD Detection**

During normal operation, the MAX5984 probes the output for a valid PD. A valid PD has a  $25k\Omega$  discovery signature characteristic as specified in the IEEE 802.3af/802.3at standard. Table 1 shows the IEEE 802.3at specification for a PSE detecting a valid PD signature.

During detection, the MAX5984 keeps the internal MOSFET off and forces two probe voltages through DET. The current through DET is measured as well as the voltage at OUT. A two-point slope measurement is used, as specified by the IEEE 802.3af/802.3at standard, to verify the device connected to the port.

An external diode, in series with the DET input, restricts PD detection to the first quadrant as specified by the IEEE 802.3af/802.3at standard. To prevent damage to non-PD devices, and to protect itself from an output short circuit, the MAX5984 limits the current into DET to less than 2mA maximum during PD detection.

In midspan mode, the MAX5984 waits at least 2.0s before attempting another detection cycle after every failed detection. The first detection, however, happens immediately after exiting a reset condition.

#### High-Capacitance Detection

The status of the LEGACY input is latched during power-up or after reset condition is cleared. The LEGACY input is internally pulled high enabling high-capacitance detection. Unless high-capacitance detection is needed, connect LEGACY to VEE to disable this function. If high-capacitance detection is enabled, PD signature capacitances up to  $47\mu\text{F}$  (typ) are accepted.

Table 1. PSE PD Detection Modes Electrical Requirements (IEEE 802.3at)

PARAMETER	SYMBOL	MIN	MAX	UNITS	ADDITIONAL INFORMATION
Open-circuit voltage	Voc		30	V	In detection mode only
Short-circuit current	Isc		5	mA	In detection mode only
Valid test voltage	VVALID	2.8	10	V	
Voltage difference between test points	ΔVTEST	1		V	
Time between any two test points	t <sub>BP</sub>	2		ms	This timing implies a 500Hz maximum probing frequency
Slew rate	VSLEW		0.1	V/µs	
Accept signature resistance	RGOOD	19	26.5	kΩ	
Reject signature resistance	RBAD	< 15	> 33	kΩ	
Open-circuit resistance	ROPEN	500		kΩ	
Accept signature capacitance	CGOOD		150	nF	
Reject signature capacitance	CBAD	10		μF	
Signature offset voltage tolerance	Vos	0	2.0	V	
Signature offset current tolerance	los	0	12	μΑ	

#### **PD Classification**

During the PD classification mode, the MAX5984 forces a probe voltage (-18V typ) at DET and measures the current into DET. The measured current determines the class of the PD. If the ILIM1 and ILIM2 pins are both left unconnected, the MAX5984 classifies the PD based on Table 33.9 of the IEEE 802.3at standard (Table 2). If the measured current exceeds 51mA, the MAX5984 does not power the PD, but returns to the idle state before attempting a new detection cycle.

#### Class 5 PD Classification

The MAX5984 supports high power beyond the IEEE 802.3at standard by providing an additional classification (Class 5) if needed. To enable Class 5 detection and select the corresponding current-limit/overcurrent thresholds, ILIM1 and ILIM2 must be set based on the combinations detailed in Table 3. Once Class 5 is

Table 2. PSE Classification of a PD (Table 33.9 of the IEEE 802.3at Standard)

MEASURED ICLASS (mA)	CLASSIFICATION
0 to 5	Class 0
> 5 and < 8	Can be Class 0 or 1
8 to 13	Class 1
> 13 and < 16	Either Class 1 or 2
16 to 21	Class 2
> 21 and < 25	Either Class 2 or 3
25 to 31	Class 3
> 31 and < 35	Either Class 3 or 4
35 to 45	Class 4
> 45 and < 51	Either Class 4 or Invalid

enabled, during classification, if the MAX5984 detects currents in excess of the Class 4 upper limit threshold, the PD is classified as a Class 5 PD. The PD is guaranteed to be classified as a Class 5 device for any classification current from 51mA up to the classification current-limit threshold.

The Class 5 overcurrent threshold and current limit is set with ILIM1 and ILIM2. ILIM1 and ILIM2 are both referenced to VEE and are internally pulled up to the digital supply. Leave ILIM1 and ILIM2 unconnected to disable Class 5 detection and to be fully compliant to IEEE 802.3at standard classification. Class 5 detection is enabled, and the corresponding overcurrent threshold and current limit is adjusted, by connecting one or both to VEE (Table 3).

#### 2-Event PD Classification

If the result of the first classification event is Class 0 through Class 3, then only a single classification event occurs, as shown in Figure 1. However, if the result is Class 4 or Class 5 (when enabled), the device performs a second classification event, as shown in Figure 2. Between the classification cycles, the MAX5984 performs a first and second mark event as required by the IEEE 802.3at standard, forcing a -9.0V probing voltage at DET. The 2-Event function is disabled by default in the MAX5984A/MAX5984B/MAX5984E. However, it is not pin-selectable in the MAX5984E.

#### **Powered State**

When the MAX5984 enters a powered state, the tFAULT and tDISC timers are reset. When the startup timer has timed out, the device enters a normal powered condition, allowing power delivery to the PD.

Table 3. Class 5 Overcurrent Threshold and Current-Limit Settings

ILIM1 CONFIGURATION	ILIM2 CONFIGURATION	OVERCURRENT THRESHOLD (mA)	CURRENT LIMIT (mA)
Unconnected	Unconnected	Class 5 disabled	Class 5 disabled
VEE	Unconnected	748	850
Unconnected	VEE	792	900
VEE	VEE	836	950

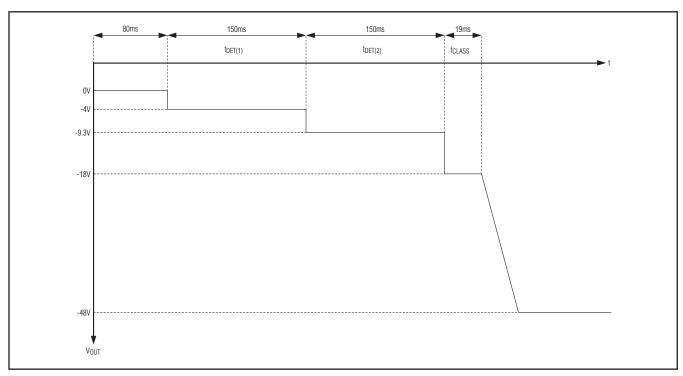


Figure 1. Detection, Classification, and Port Power-Up Sequence

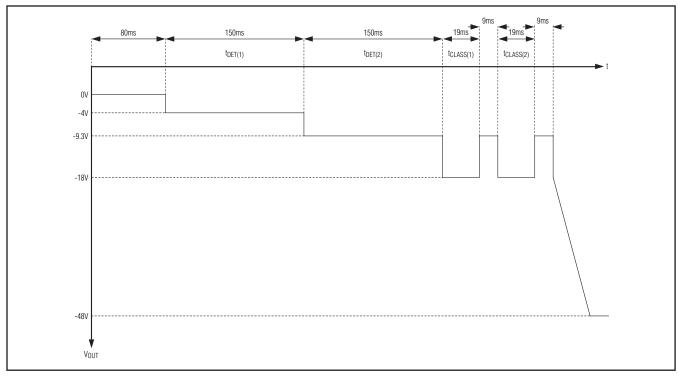


Figure 2. Detection, 2-Event Classification, and Port Power-Up Sequence

#### **Overcurrent Protection**

The MAX5984 has an internal sense resistor, RSENSE (see the *Simplified Diagram*), connected between the source of the internal MOSFET and VEE to monitor the load current. Under normal operating conditions, the current through RSENSE (IRSENSE) never exceeds the threshold ILIM. If IRSENSE exceeds ILIM, an internal current-limiting circuit regulates the gate voltage of the internal MOSFET, limiting the current. During transient conditions, if IRSENSE exceeds ILIM by more than 2A, a fast pulldown circuit activates to quickly recover from the current overshoot.

In the normal powered state, the MAX5984 checks for overcurrent conditions, as determined by I<sub>CUT</sub> = ~88% of I<sub>LIM</sub>. The tF<sub>AULT</sub> counter sets the maximum allowed continuous overcurrent period. This timer is incremented both in startup and in normal powered state, but under different conditions. During startup, the counter increases when I<sub>RSENSE</sub> exceeds I<sub>LIM</sub>, while in the normal powered state the counter increases when I<sub>RSENSE</sub> exceeds I<sub>CUT</sub>. It decreases at a slower pace when I<sub>RSENSE</sub> drops below I<sub>LIM</sub> or I<sub>CUT</sub>. A slower decrement for the tFAULT counter allows for detection of repeated short-duration overcurrent events. When the counter reaches

the tFAULT limit, the MAX5984 powers down the port. For a continuous overstress, a fault occurs exactly after a period of tFAULT.

After a power-off due to an overcurrent fault, the tFAULT timer is not immediately reset but starts decrementing. The MAX5984 allows the port to be powered on only when the tFAULT counter reaches zero. This feature sets an automatic port power duty-cycle protection to the internal MOSFET to avoid overheating.

In the normal powered state, the I<sub>LIM</sub> and I<sub>CUT</sub> thresholds are set automatically according to the classification result (see Table 2 for classification results based on detection current and the *Electrical Characteristics* table for the corresponding thresholds). During startup, I<sub>LIM</sub> is always set to 420mA regardless of the detected class.

### **Foldback Current**

During startup and normal operation, an internal circuit senses the port voltage and reduces the current-limit value and the overcurrent threshold when (VAGND - VOUT) < 27V. The foldback function helps to reduce the power dissipation on the internal MOSFET. The current limit eventually reduces down to ITH\_FB when (VAGND - VOUT) < 10V (Figure 3).

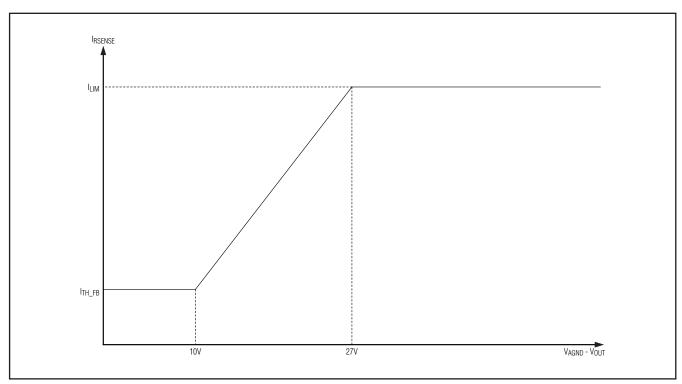


Figure 3. Foldback Current Characteristics

### **Digital Logic**

The MAX5984 internally generates digital supplies (referenced to VEE) to power the internal logic circuitry. All logic inputs and outputs are referenced to VEE. See the *Electrical Characteristics* table for digital input thresholds. If digital logic inputs are driven externally, the nominal digital logic level is 3.3V.

### **Undervoltage and Overvoltage Protection**

The MAX5984 contains undervoltage and overvoltage protection features. An internal VEE undervoltage lockout (VEE\_UVLO) circuit keeps the port off and the MAX5984 in reset until VAGND - VEE exceeds 28.5V (typ) for more than 2.5ms. An internal VEE overvoltage (VEE\_OV) circuit shuts down the port when (VAGND - VEE) exceeds 62.5V (typ).

#### **DC Disconnect Monitoring**

Force OSC to VEE and power or reset the device to activate DC load-disconnect monitoring. If IRSENSE (the current across RSENSE) falls below the DC load-disconnect threshold, IDCTH, for more than tDISC, the device turns off port power.

#### **AC Disconnect Monitoring**

The MAX5984 features AC load-disconnect monitoring. Bypass OSC with a 100nF (±10% tolerance) external capacitor to VEE and power or reset the device to enable AC disconnect. When AC disconnect is enabled.

a blocking diode in series to OUT and an RC circuit in parallel to the DET diode must be used, as shown in Figure 7.

The AC disconnect uses an internal triangle wave generator to supply the probing signal. Then the resulting 4VP-P amplitude wave is forced on DET. The common mode of the output signal probed on DET is 5V below AGND. If the AC current peak into DET falls below IACTH for more than tDISC, the device powers down the port.

### **PWM and LED Signals**

The MAX5984 includes a multifunction LED driver to inform the user of the port status. LED is an open-drain, multifunction output referenced to VEE and can sink up to 10mA (typ) while driving an external LED. The LED is turned on when the port is connected to a valid PD and powered. If the port is not powered or is disconnected, the LED will be off.

For two other conditions, the MAX5984 blinks a code to communicate the port status. A series of two flashes indicates an overcurrent fault occurred during port power-on, and has a timing characteristic detailed by Figure 4. A series of five flashes indicates that during detection an invalid low or high discovery signature resistance was detected and has a timing characteristic detailed by Figure 5.

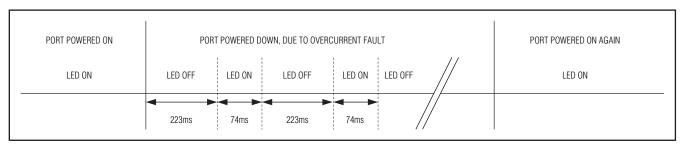


Figure 4. LED Code Timing for Overcurrent Fault During Port Power-On

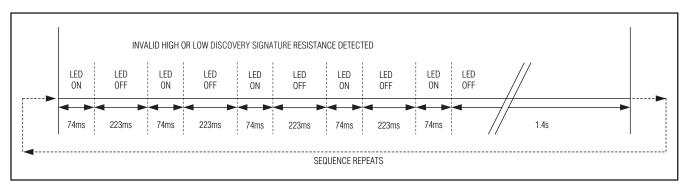


Figure 5. LED Code Timing for Detection Fault Due to High- or Low-Discovery Signature Resistance

The MAX5984 also contains an internal square wave, PWM signal generator. The PWM runs at a typical frequency of 25kHz with an approximate typical duty cycle of 6.25%. PWMEN is used to enable or disable the PWM. PWMEN is internally pulled up to the digital supply, and can be left unconnected to enable the internal PWM. When enabled, the LED pulses are driven by the PWM to reduce the power dissipation and increase the system efficiency. Force PWMEN low to disable the internal PWM; the LED is then driven directly.

#### Thermal Shutdown

If the MAX5984 die temperature reaches +150°C, an overtemperature fault is generated and the device shuts down. The die temperature must cool down below 130°C to remove the overtemperature fault condition. After a thermal shutdown condition clears, the device is reset.

## Applications Information

### **Layout Procedure**

Careful PCB layout is critical to achieve high efficiency and low EMI. Follow these layout guidelines for optimal performance.

- 1) Place the input bypass capacitance and the output bypass capacitor (0.1µF ceramic capacitor from AGND to OUTP) as close as possible to the MAX5984.
- 2) Use large SMT component pads for power dissipating devices such as the MAX5984 and the external diodes in the high-power path.
- 3) Use short, wide traces whenever possible for high-power paths.
- 4) Use the MAX5971 Evaluation Kit as a design and layout reference.
- 5) The exposed pad (EP) must be soldered evenly to the PCB ground plane for proper operation and power dissipation. Use multiple vias beneath the exposed pad for maximum heat dissipation. A 1.0mm to 1.2mm pitch is the recommended spacing for these vias and they should be plated (1oz copper) with a small barrel diameter (0.30mm to 0.33mm).

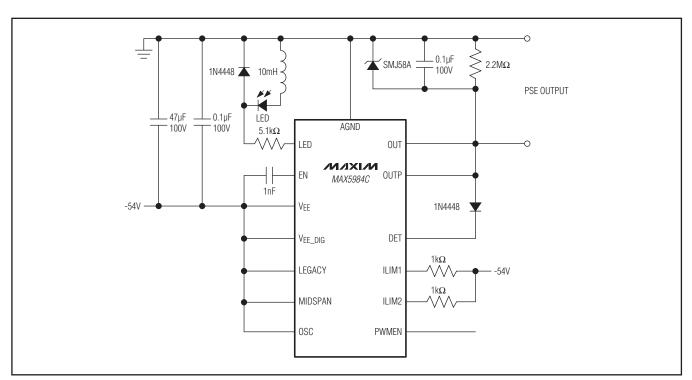


Figure 6. Typical Operating Circuit 1 (DC Load Removal Detection, Internal PWM Enabled for LED Indication, and Class 5 Detection Enabled)

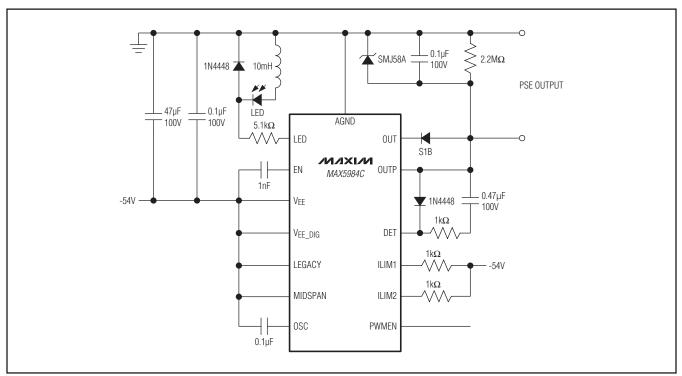


Figure 7. Typical Operating Circuit 2 (AC Load Removal Detection, Internal PWM Enabled for LED Indication, and Class 5 Detection Enabled)

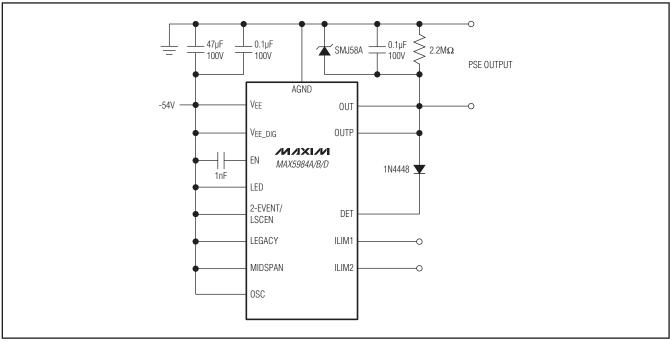


Figure 8. Typical Operating Circuit 3 (IEEE 802.3at Compliant, Minimal Application Circuit with DC Load Removal Detection and No LED Indication)

**Chip Information** 

## **Package Information**

For the latest package outline information and land patterns (footprints), go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
28 TQFN-EP	T2855+6	<u>21-0140</u>	

MIXIM

PROCESS: BICMOS